

Abstract

An inexpensive, accurate, and reliable semiconductor physical quantity sensor having improved resistance to noise is provided, wherein pads that have been pulled down to ground inside a semiconductor chip are arranged closer to a ground pad, while pads and that have been pulled up to a power supply inside the chip are arranged closer to a power supply pad. Of the digital input/output pads that have undergone digital trimming to obtain a predetermined output, the pulled-down pads and the ground pad are electrically connected to a ground terminal outside the chip via internal exposed portions, wires, and a ground-connecting external wire. The pulled-up pads and the power supply pad are electrically connected to a power supply terminal outside the chip via the internal exposed portions, the wires, and a power-supply-connecting external wire. Terminals may be electrically connected together on a package or a mounting substrate.

2025 RELEASE UNDER E.O. 14176